ΡΛΝ	ĴΪΤ
	SEMI CONDUCTOR

Unit : inch(mm)

0.024(0.60)

0.019(0.50)

3

D2

#### **PJX8838 50V N-Channel Enhancement Mode MOSFET- ESD Protected** SOT-563 Voltage 50 V Current 360mA 0.011(0.27) 0.006(0.17) 0.067(1.70) 0.059(1.50) Features 0.035(0.90) RDS(ON), VGS@10V, ID@500mA<1.45Ω</li> RDS(ON), VGS@4.5V, ID@200mA<1.95Ω 0.052(1.30) 0.043(1.10) 0.067(1.70) RDS(ON), VGS@2.5V, ID@100mA<4.0Ω . 0.059(1.50) RDS(ON), VGS@1.8V, ID@10mA<6.0Ω • 0.007(0.17) Advanced Trench Process Technology ESD Protected 2KV HBM • Specially Designed for Relay driver, Speed line drive, etc. • Lead free in compliance with EU RoHS 2011/65/EU directive 0.012(0.30) Green molding compound as per IEC61249 Std. (Halogen Free) D1 G2 Mechanical Data 6 5 Case: SOT-563 Package • Terminals: Solderable per MIL-STD-750, Method 2026 . Approx. Weight: 0.00009 ounces, 0.0026 grams . 2 Marking: X38

#### Maximum Ratings and Thermal Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

PARAMETER		SYMBOL	LIMIT	UNITS
Drain-Source Voltage		V <sub>DS</sub>	50	V
Gate-Source Voltage		V <sub>GS</sub>	<u>+</u> 20	V
Continuous Drain Current		Ι <sub>D</sub>	360	mA
Pulsed Drain Current		I <sub>DM</sub>	1200	mA
Power Dissipation	T <sub>A</sub> =25°C		300	mW
	Derate above 25°C	P <sub>D</sub>	2.4	mW/°C
Operating Junction and Storage Temperature Range		TJ,TSTG	-55~150	°C
Typical Thermal resistance - Junction to Ambient <sup>(Note 3)</sup>		$R_{ extsf{ heta}JA}$	417	°C/W



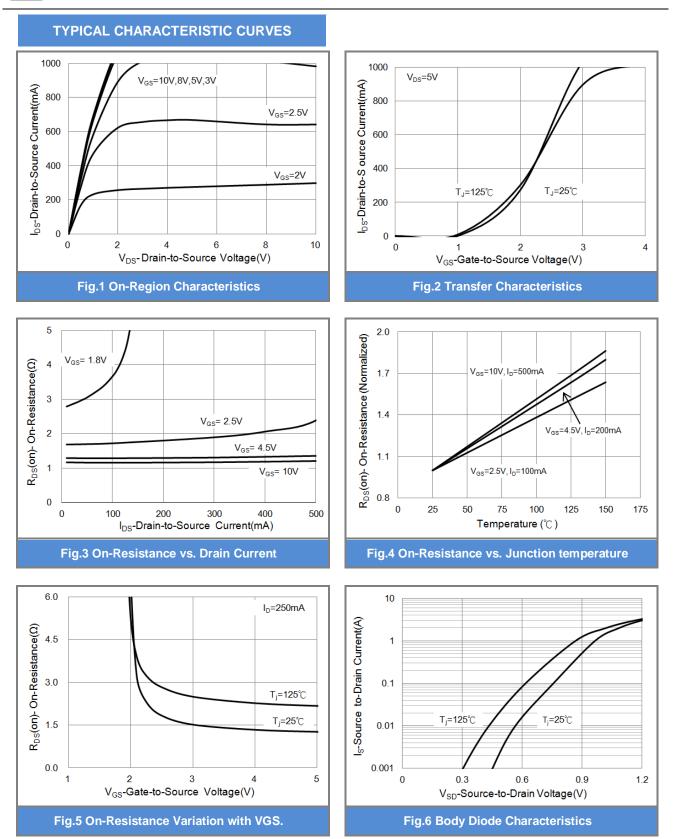
### Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

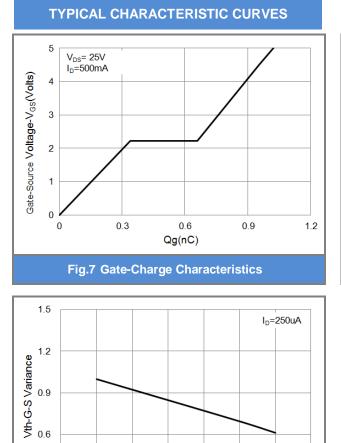
PARAMETER	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNITS
Static						
Drain-Source Breakdown Voltage	$BV_{DSS}$	V <sub>GS</sub> =0V,I <sub>D</sub> =250uA	50	-	-	V
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=250$ uA	0.5	0.86	1.0	V
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	$V_{GS}$ =10V,I <sub>D</sub> =500mA	-	1.2	1.45	Ω
		$V_{GS}$ =4.5V,I <sub>D</sub> =200mA	-	1.3	1.95	
		V <sub>GS</sub> =2.5V,I <sub>D</sub> =100mA	-	1.7	4.0	
		V <sub>GS</sub> =1.8V,I <sub>D</sub> =10mA	-	4.0	6.0	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V	-	-	1	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = <u>+</u> 20V,V <sub>DS</sub> =0V	-	-	<u>+</u> 10	uA
Dynamic (Note 4)						
Total Gate Charge	Qg	V <sub>DS</sub> =25V, I <sub>D</sub> =500mA, V <sub>GS</sub> =4.5V	-	0.95	-	nC
Gate-Source Charge	$Q_gs$		-	0.34	-	
Gate-Drain Charge	$Q_gd$		-	0.32	-	
Input Capacitance	Ciss	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHZ	-	36	-	pF
Output Capacitance	Coss		-	11	-	
Reverse Transfer Capacitance	Crss		-	6.6	-	
Turn-On Delay Time	td <sub>(on)</sub>		-	2.3	-	
Turn-On Rise Time	tr	$V_{DD}=25V, I_{D}=500mA,$	-	20	-	ns
Turn-Off Delay Time	td <sub>(off)</sub>	$V_{GS}=10V,$ $R_G=6\Omega^{(Note 1,2)}$	-	7	-	
Turn-Off Fall Time	tf	R <sub>G</sub> =612	-	20	-	
Drain-Source Diode						
Maximum Continuous Drain-Source Diode Forward Current	I <sub>S</sub>		-	-	500	mA
Diode Forward Voltage	$V_{SD}$	I <sub>S</sub> =500mA, V <sub>GS</sub> =0V	-	0.9	1.5	V

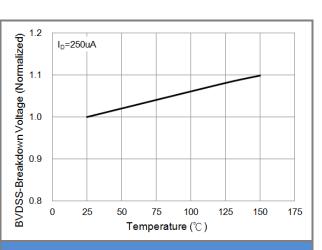
NOTES :

- 1. Pulse width</br>
- 2. Essentially independent of operating temperature typical characteristics.
- 3. R<sub>0JA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. mounted on a 1 inch square pad of copper
- 4. Guaranteed by design, not subject to production testing.

### PJX8838









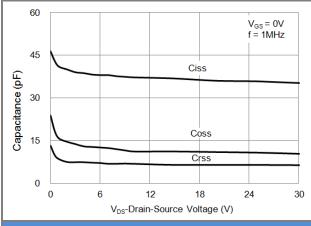


Fig.10 Capacitance vs. Drain-Source Voltage.

0.3

0

25

50

75

Fig.9 Threshold Voltage Variation with Temperature.

Temperature (℃)

100

125

150

175

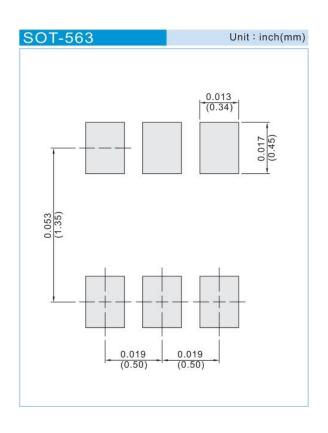




#### PART NO PACKING CODE VERSION

Part No Packing Code	Package Type	Packing type	Marking	Version
PJX8838_R1_00002	SOT-563	8K pcs / 7" reel	X38	Halogen free
PJX8838_R2_00002	SOT-563	20K pcs / 13" reel	X38	Halogen free

#### MOUNTING PAD LAYOUT







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